## **CURRENTLY PENDING CLAIMS**

What follows is a listing of claims currently pending in this application. Claims 41-46, 48-54, and 58 have been cancelled. Please amend claims 47, 56, 59, and 60 as shown below.

1-46. (Cancelled)

- 47. (Currently amended) The memory defined by claim 46, A memory disposed above a substrate comprising:
  - a plurality of memory levels organized as first alternate levels disposed between second alternate levels;
  - a plurality of two terminal memory cells incorporated into each of the levels;

    one terminal of the cells in each of the first alternate levels and each of the second

    alternate levels being coupled to first lines shared by the cells in each pair of

    first and second alternate levels;
  - the other terminal of the cells in each of the first alternate levels being coupled to second lines; and
  - the other terminal of the cells in each of the second alternate levels being coupled to third lines.

wherein each cell comprises, when programmed, a diode and an antifuse layer, wherein the diodes comprise an N- region and a P+ region,

wherein the N- regions in the diodes in at least one of the first and second alternate levels has a smaller cross-section than the P+ region.

48-54. (Cancelled)

55. (Previously presented) A memory disposed above a substrate comprising:

a plurality of memory levels organized as first alternate levels disposed between second alternate levels;

a plurality of two terminal memory cells incorporated into each of the levels;

one terminal of the cells in each of the first alternate levels and each of the second alternate levels being coupled to first lines shared by the cells in each pair of first and second alternate levels;

the other terminal of the cells in each of the first alternate levels being coupled to second lines;

the other terminal of the cells in each of the second alternate levels being coupled to third lines; and

an oxide layer disposed between each of the pair of first and second alternate levels.

56. (Currently amended) The memory defined by claim 54 55, wherein each cell comprises, when programmed, a diode and a breached antifuse layer.

- 57. (Previously presented) The memory defined by claim 56, wherein at least some of the diodes comprise two regions, one having a smaller cross-section than the other.
- 58. (Cancelled)
- 59. (Currently amended) The memory defined by claim 58, A memory disposed above a substrate comprising:

a plurality of memory levels, each level having a plurality of two terminal memory cells;

each of the memory cells comprising a diode and a breached antifuse layer, when programmed;

one terminal of the cells in first alternate levels and second alternate levels of the memory levels being coupled to first lines, shared by the cells;

the other terminal of the cells in the first alternate levels being coupled to second lines in each of the first alternate levels; and

the other terminal of the cells in the second alternate levels being coupled to third lines in each of the second levels,

such that cells in paired first and second alternate levels are coupled to shared first line and one of the second and third lines,

wherein at least some of the diodes have two regions one of which has a smaller cross-section than the other.

- 60. (Currently amended) In a three-dimensional memory array, two adjacent memory levels comprising:
  - a first plurality of parallel, spaced-apart rail-stacks;
  - a second plurality of parallel, spaced-apart rail-stacks perpendicular to the first rail stacks disposed above the first rail-stacks;
  - a third plurality of parallel, spaced-apart rail-stacks perpendicular to the second rail-stacks disposed above the second rail-stacks, the first, second, and third rail-stacks being of approximately the same height;

the first rail-stacks and a first portion of a second rail-stacks defining first cells in one of the two levels and the third rail-stacks and a second portion of the second rail-stacks defining second cells in the other level of the memory,

the third second rail-stacks including conductors shared by the first and second cells.

- 61. (Previously presented) The array of claim 60, wherein each cell comprises a diode and a breached antifuse layer, when programmed.
- 62. (Previously presented) The array of claim 61, wherein each diode includes a P+N-junction.
- 63. (Previously presented) The array of claim 62, wherein the antifuse layer of the cells comprises silicon dioxide.